1	L Number	Hits	Search Text	DB	Time stamp
Property				USPAT;	2003/01/23 11:20
DERMENT;   IMM TIDE	_			US-PGPUB;	
Section   Sect				EPO; JPO;	
2   35   \$252854.NRPN.   USPĀT   2003/01/23 11:24   2003/01/23 11:25				DERWENT;	
1				IBM_TDB	
1	2	35	5252854.URPN.	USPAT	2003/01/23 10:42
3   6081029.NEPN.   USPAT   2003/01/23 11:24   2003/01/23 11:25   20		1	("6081029").PN.	USPAT	2003/01/23 11:25
1		3	6081029.URPN.	USPAT	2003/01/23 11:24
297   203/01/23 11:39   203/01/23 11:39   203/01/23 11:39   203/01/23 11:39   203/01/23 11:39   203/01/23 11:39   203/01/23 11:40   203/01/23 11:50   203/		1	("6452278").PN.	USPAT	2003/01/23 11:27
144   438/977.ccls. and lead\$2   US-PGPUB; EPC; JPC; DERMENT; IBM TDB USPAT;	1	3153	257/666.ccls.	USPAT;	2003/01/23 11:39
144   438/977.ccls. and lead\$2   DERMENT; IBM TDB USPAT; US-CPUB; EPO; JPO; DERMENT; IBM TDB USPAT;				US-PGPUB;	
The tensor of				EPO; JPO;	
144   438/977.ccls. and lead\$2   USPĀT; US-PGFUB; EPO; JPO; DERWENT; IBM TDB USPĀT; USPĀT USPĀT; US-PGFUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGFUB; EPO; JPO; DERWENT; IBM TDB USPĀT; USPĀT USPĀT USPĀT; USPĀT U				DERWENT;	ŀ
Second Content of the content of t				IBM_TDB	
S	7	144	438/977.ccls. and lead\$2	USPAT;	2003/01/23 11:40
S					
139				EPO; JPO;	
S				DERWENT;	:
Comparison   Com				IBM_TDB	
Second   Comparison   Compari	8	139	(438/977.ccls. and lead\$2) and		2003/01/23 13:18
			(@ad<20000425)	US-PGPUB;	
1				EPO; JPO;	
1				DERWENT;	
1 ("6247229") PN. 12 2699 6247229.URPN. 13 2699 (Chip and (metal\$4 near (substrate or base)) and wire  14 (Chip and (metal\$4 near (substrate or base)) and wire) and ((remov\$3 or thin\$4) near (substrate or base)) and wire) and ((remov\$3 or thin\$4) near (substrate or base)) and wire) and ((remov\$3 or thin\$4) near (substrate or base)) and wire) and ((remov\$3 or thin\$4) near (substrate or base)) and encapsula\$3 per po;					
12	9	1	("20020056926").PN.	US-PGPUB	
12	10	1	("6247229").PN.	USPAT	2003/01/23 11:50
and wire  and wire    September   Septembe	11	5	6247229.URPN.	USPAT	
13   436   (chip and (metal\$4 near (substrate or base))   and wire) and ((remov\$3 or thin\$4) near (substrate or base))   USPAT; US-PGPUB; EPO; JPO; DERWENT; IEM_TDB USPAT; US-PGPUB; EPO; JPO; JPO; DERWENT; IEM_TDB USPAT USPAT; US-PGPUB; EPO; JPO; DERWENT; IEM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IEM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IEM_TDB USPAT;	12	2869	chip and (metal\$4 near (substrate or base))		2003/01/23 11:52
13   436   (chip and (metal\$4 near (substrate or base))   and wire) and ((remov\$3 or thin\$4) near (substrate or base))   (chip and (metal\$4 near (substrate or base))   (chip and wire) and ((remov\$3 or thin\$4)   (substrate or base))   (chip and (metal\$4 near		,	and wire	1	
13   436   (chip and (metal\$4 near (substrate or base))   USPĀT;   US-PGPUB;   EPO; JPO;   DERWENT;   IBM TDB   USPĀT;   USPĀT;   USPĀT;   USPĀT;   USPĀT   USPĀT;   US-PGPUB;   EPO; JPO;   DERWENT;   IBM TDB   USPĀT;   US-PGPUB;   EPO; JPO;   DERWENT;   US-PGPUB;   EPO; JPO;   DERWE					
13					
and wire) and ((remov\$3 or thin\$4) near (substrate or base))  14  105 ((chip and (metal\$4 near (substrate or base)) and wire) and ((remov\$3 or thin\$4) near (substrate or base)) and encapsula\$3  15  69 (((chip and (metal\$4 near (substrate or base))) and encapsula\$3					
Substrate or base )	13	436			2003/01/23 13:16
14				1	
105			(substrate or base))		
14				· ·	
base) and wire) and ((remov\$3 or thin\$4)   US-PGPUB;   EPO; JPO; DERWENT;   IBM_TDB   USPAT   USPAT   2003/01/23 12:01   USPAT   2003/01/23 12:01   USPAT   2003/01/23 12:03   USPAT   USPAT   2003/01/23 12:03   USPAT   USPAT   2003/01/23 12:03   USPAT   USPAT   2003/01/23 12:03   USPAT   2003/01/23 12:03   USPAT   USPAT   2003/01/23 12:03   USPAT   USPAT   2003/01/23 12:04   USPAT   USPAT   2003/01/23 12:04   USPAT   USPAT   2003/01/23 12:05   USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB   USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB					
near (substrate or base))) and encapsula\$3	14	105	((chip and (metal\$4 near (substrate or	i ·	2003/01/23 11:56
DERMENT;   IBM_TDB   USPAT;   US-PGPUB;   EPO; JPO;   DERMENT;   IBM_TDB   USPAT;   US-PGPUB;   EPO; JPO;   DERMENT;   IBM_TDB   USPAT   USP					
15			near (substrate or base))) and encapsula\$3	1	
15				1	
base)   and wire) and ((remov\$3 or thin\$4)   US-PGPUB; near (substrate or base))   and encapsula\$3)   EPO; JPO; DERWENT; IBM TDB   USPAT   2003/01/23 12:00   USPAT   2003/01/23 12:01   USPAT   2003/01/23 12:01   USPAT   2003/01/23 12:01   USPAT   2003/01/23 12:01   USPAT   2003/01/23 12:03   USPAT   2003/01/23 12:04   USPAT   2003/01/23 12:04   USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB   USPAT; US-PGPUB; EPO; JPO; DERWENT; ISPAT; U			///-him and /matality many (substrate or		2002/01/22 11.50
near (substrate or base))) and encapsula\$3)	15	69		1	2003/01/23 11:59
and (@ad<20000425)  17					
1					
17			and (wad(20000425)		
18	17	1	("6380062") PN		2003/01/23 12:00
19 0 6380062.URPN. 20 0 6380062.URPN. 21 0 6380062.URPN. 21 0 6380062.URPN. 20 ((thick and thin) near lead) and (die or Chip) and wire\$5  22 8712 lead and (die or chip) and wire\$5 and encapsula\$4  23 1557 (lead and (die or chip) and wire\$5 and encapsula\$4) and (etch\$3 or remov\$3 or thin\$4) near (substrate or base or metal\$4))  USPAT USPAT 2003/01/23 12:03 2003/01/23 12:03 2003/01/23 12:03 2003/01/23 12:03 2003/01/23 12:03 2003/01/23 12:04 2003/01/23 12:05	1			1	
20	1		l '		
21 0 6380062.URPN. 20 ((thick and thin) near lead) and (die or Chip) and wire\$5 US-PGPUB; EPO; JPO; DERWENT; IBM_TDB 22 8712 lead and (die or Chip) and wire\$5 and encapsula\$4 US-PGPUB; EPO; JPO; DERWENT; IBM_TDB 23 1557 (lead and (die or chip) and wire\$5 and encapsula\$4) and ((etch\$3 or remov\$3 or thin\$4) near (substrate or base or metal\$4)) USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB 2003/01/23 12:03 2003/01/23 12:04 2003/01/23 12:05 2003/01/23 12:05 2003/01/23 12:05 2003/01/23 12:05 2003/01/23 12:05	i i	_			
16 20 ((thick and thin) near lead) and (die or chip) and wire\$5 US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; USPAT	1	_	1		1
chip) and wire\$5  chip) and wire\$5  US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT;	1	_			
22 8712 lead and (die or chip) and wire\$5 and encapsula\$4 USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; USPGPUB; EPO; JPO; DERWENT;					
DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT;					
22 8712 lead and (die or chip) and wire\$5 and encapsula\$4 USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; USPGPUB; EPO; JPO; DERWENT;					1
22 8712 lead and (die or chip) and wire\$5 and encapsula\$4 USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; encapsula\$4) and (die or chip) and wire\$5 and encapsula\$4) and ((etch\$3 or remov\$3 or thin\$4) near (substrate or base or metal\$4)) EPO; JPO; DERWENT;				1	
encapsula\$4  US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; encapsula\$4) and ((etch\$3 or remov\$3 or encapsula\$4) and ((etch\$3 or remov\$3 or thin\$4) near (substrate or base or metal\$4))  EPO; JPO; DERWENT;	22	8712	lead and (die or chip) and wire\$5 and		2003/01/23 12:05
23 1557 (lead and (die or chip) and wire\$5 and encapsula\$4) and ((etch\$3 or remov\$3 or thin\$4) near (substrate or base or metal\$4)) EPO; JPO; DERWENT;				1	, , == ==
23 1557 (lead and (die or chip) and wire\$5 and encapsula\$4) and ((etch\$3 or remov\$3 or thin\$4) near (substrate or base or metal\$4)) DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;					
23   1557 (lead and (die or chip) and wire\$5 and encapsula\$4) and ((etch\$3 or remov\$3 or thin\$4) near (substrate or base or metal\$4))   EPO; JPO; DERWENT;					
23				1	
encapsula\$4) and ((etch\$3 or remov\$3 or US-PGPUB; thin\$4) near (substrate or base or metal\$4)) EPO; JPO; DERWENT;	23	1557	(lead and (die or chip) and wire\$5 and		2003/01/23 12:08
thin\$4) near (substrate or base or metal\$4)) EPO; JPO; DERWENT;			encapsula\$4) and ((etch\$3 or remov\$3 or	US-PGPUB;	
				EPO; JPO;	
IBM_TDB				1	
				IBM_TDB	

Page 1

24	1102	((lead and (die or chip) and wire\$5 and	USPAT;	2003/01/23 12:28
24	1102	encapsula\$4) and ((etch\$3 or remov\$3 or	US-PGPUB;	2003/01/23 12:20
		thin\$4) near (substrate or base or	EPO; JPO;	
		metal\$4))) and (@ad<20000425)	DERWENT;	
		meta154))) and (wad<20000425)	IBM TDB	
	0.50	(/-1-ii-) //	USPAT;	2003/01/23 12:47
25	960	((chip or die) near pad) and ((etch\$3 or	US-PGPUB;	2003/01/23 12:47
		remov\$3 or thin\$4) near (substrate or base	EPO; JPO;	
		or metal\$4))	DERWENT;	
			IBM TDB	
		00000074670 17001	USPAT	2003/01/23 12:43
26		20020074672.URPN.	USPAT	2003/01/23 12:43
27		("6211462").PN.		1 ' '
28	0	(think near pad) and lead and (chip or die)	USPAT;	2003/01/23 13:13
		and encapsula\$4	US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
		(, ), i = 1,,, d  , d	USPAT;	2003/01/23 13:15
29	21	(thick near pad) and lead and (chip or die)	1	2003/01/23 13:15
		and encapsula\$4	US-PGPUB; EPO; JPO;	
			DERWENT:	
			IBM TDB	
20	2200	141	USPAT:	2003/01/23 13:15
30	2399	leadless and chip	US-PGPUB:	2003/01/23 13:15
			EPO; JPO; DERWENT;	
			1	
22	241	(leadless and chip) and ((remov\$3 or thin\$4)	IBM_TDB USPAT;	2003/01/23 13:18
32	241	near (metal\$4 or substrate or base))	US-PGPUB;	2003/01/23 13:18
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
33	207	((leadless and chip) and ((remov\$3 or	USPAT;	2003/01/23 13:19
33	207	thin\$4) near (metal\$4 or substrate or	US-PGPUB;	2003/01/23 13:19
		base))) and (@ad<20000425)	EPO; JPO;	
		Dase/// and (wad<20000425)	DERWENT;	
			IBM TDB	
	l		םתו_ווםד	

Search History 1/23/03 1:26:26 PM Page 2